

In the Specification:

Please replace the paragraph beginning at page 8, line 12, with the following rewritten paragraph:

-- Figure 5 shows interposer 1 attached to chip die 23 by solder connections ~~25~~, shown by cross-hatching. The attachment of interposer 1, as shown in Figure 1, to chip die 23 is achieved by positioning interposer pads 7 against conventional corresponding high melt (250 - 360°C) C-4 solder bumps, previously attached to BLM pads 27 on chip die 23 in conventional manner. Upon heating, the high melt C-4 solder bumps collapse and solder is drawn through the respective copper plated vias 5 to copper pads 9 on the bottom surface of the interposer to form solder connectors. A solder stop layer may be temporarily positioned on the bottom surface of the interposer to limit the solder flow to the surface of pads 9. Thereafter the layer can be removed to expose pads 9. Alternatively, solder flow may be allowed to flow past the surface of pads 9 and, upon cooling, excess solder is trimmed flush with the surface pads. --

Please replace the paragraph beginning at page 10, line 19, with the following rewritten paragraph:

-- Figure 8 shows the manner in which the ~~arrangement~~ solder connections 25,
shown in cross-hatching, of Figure 5 ~~is~~ are attached to a circuit card. Low melt eutectic
solder balls 29 in Figure 5 are first aligned in contact with chip pads 31 on circuit card 33.
Upon heating, the solder balls melt and after cooling become soldered to pads 31. The
same process is used in Figures 9 and 10 to attach the interposer/chip die structure of
Figures 6 and 7 to circuit card 33. --